SILICON POWER

November 14th, 2019 **PCN20191114**

Process Change Notification (PCN)

Change Detail:
Be advised, Silicon Power Corporation has added a 25µm (~0.001”) silicon wafer back-grinding process step to the wafer production process of the SP205 product family.

Part Number	Introduction of Change	Semiconductor Lot
SP205-01	Date Code 1944	219-506174.000
SP205-01T	Date Code 1944	219-506174.000

Purpose(s) of Change:

1. To improve uniformity of the pre-metalized back-side surface of the silicon wafer
2. To improve sputtered solderable metal adhesion to the silicon wafer
3. Yields a more consistent ohmic contact of back-side metal to the silicon wafer
4. To Improve overall product yield

Impact on Performance: Minimizes capacitor discharge test variability

Data Sheet Changes: None

Process change evaluated and samples tested with positive results by: Defense Micro Electronics Activity, McClellan, CA 95652-2100

Respectfully,

William J. Hiltner
Chief Operating Officer & General Manager
Silicon Power Corporation
whiltner@siliconpower.com
(610) 407-4700